RELIABILITY REPORT

FOR

MAX1763ExE

PLASTIC ENCAPSULATED DEVICES

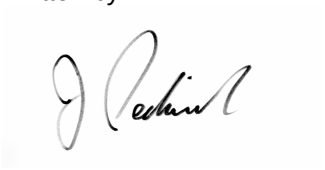
August 8, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



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Conclusion

The MAX1763 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX1763 is a high-efficiency, low-noise, step-up DC-DC converter intended for use in battery-powered wireless applications. This device maintains exceptionally low quiescent supply current (110µA) despite its high 1MHz operating frequency. Small external components and a tiny package make this device an excellent choice for small hand-held applications that require the longest possible battery life.

The MAX1763 uses a synchronous-rectified pulse-width-modulation (PWM) boost topology to generate 2.5V to 5.5V outputs from a wide range of input sources, such as one to three alkaline or NiCd/NiMH cells or a single Lithium-ion (Li+) cell. Maxim's proprietary Idle Mode™ circuitry significantly improves efficiency at light load currents while smoothly transitioning to fixed-frequency PWM operation at higher load currents to maintain excellent full-load efficiency. Low-noise, forced-PWM mode is available for applications that require constant-frequency operation at all load currents. The MAX1763 may also be synchronized to an external clock to protect sensitive frequency bands in communications equipment.

The MAX1763 includes an on-chip linear gain block that can be used to build a high-power external linear regulator or as a low-battery comparator. Soft-start and current limit functions permit optimization of efficiency, external component size, and output voltage ripple.

The MAX1763 is available in a space-saving 16-pin QSOP package or a high-power (1.5W) 16-pin TSSOP-EP package.

B. Absolute Maximum Ratings

Item	Rating
ONA, ONB, AO, OUT to GND	0.3V, +6V
PGND to GND	±0.3V
LX to PGND	-0.3V to (VPOUT + 0.3V)
CLK/SEL, REF, FB, ISET, POUT, AIN to GND	-0.3V to (VOUT + 0.3V)
POUT to OUT	±0.3V
Operating Temperature Range	-40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C
Continuous Power Dissipation	
16-Pin QSOP	667mW
16-Pin TSSOP-EP	1500mW
Derates above +70°C	
16-Pin QSOP	8.7mW/°C
16-Pin TSSOP-EP	19.0mW/°C

II. Manufacturing Information

A. Description/Function:	1.5A, Low-Noise, 1MHz, Step-Up DC-DC Converter
B. Process:	B8 - Standard .8 micron silicon gate CMOS
C. Number of Device Transistors:	1530
D. Fabrication Location:	California, USA
E. Assembly Location:	Thailand, Malaysia, Korea or Philippines
F. Date of Initial Production:	July, 2000

III. Packaging Information

	16-Lead QSOP	**16-Lead TSSOP**
A. Package Type:		
B. Lead Frame:	Copper	Copper
C. Lead Finish:	Solder Plate	Solder Plate
D. Die Attach:	Silver-filled Epoxy	Silver-filled Epoxy
E. Bondwire:	Gold (1.3 mil dia.)	Gold (1.2 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	Buildsheet # 05-1101-0127	Buildsheet # 05-1101-0128
H. Flammability Rating:	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1	Level 1

IV. Die Information

A. Dimensions:	78 x 94 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Copper/Si
D. Backside Metallization:	None
E. Minimum Metal Width:	.8 microns (as drawn)
F. Minimum Metal Spacing:	.8 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts: Jim Pedicord (Manager, Reliability Operations)
Bryan Preeshl (Executive Director of QA)
Kenneth Huening (Vice President)

B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.

C. Observed Outgoing Defect Rate: < 50 ppm

D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4389 \times 80 \times 2}$$

(Chi square value for MTTF upper limit)

Temperature Acceleration factor assuming an activation energy of 0.8eV

$\lambda = 13.57 \times 10^{-9}$ $\lambda = 13.57$ F.I.T. (60% confidence level @ 25°C)

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on rejects from lots exceeding this level. The attached Burn-In Schematic (Spec. # 06-5482) shows the static circuit used for this test. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1M**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The PX92 die type has been found to have all pins able to withstand a transient pulse of ±1500V, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of ±250mA.

Table 1
Reliability Evaluation Test Results

MAX1763ExE

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		155	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	TSSOP QSOP	77 77	0 0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Process/Package data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.
2/ No connects are not to be tested.
3/ Repeat pin combination I for each named Power supply and for ground

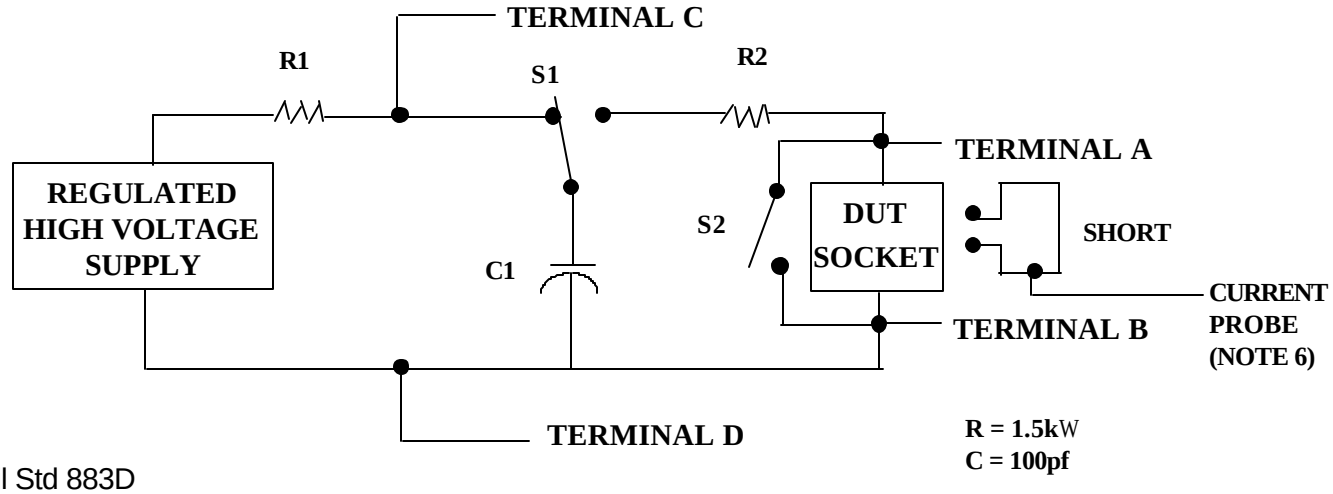
(e.g., where V_{PS1} is V_{DD}, V_{CC}, V_{SS}, V_{BB}, GND, $+V_S$, $-V_S$, V_{REF}, etc).

3.4 Pin combinations to be tested.

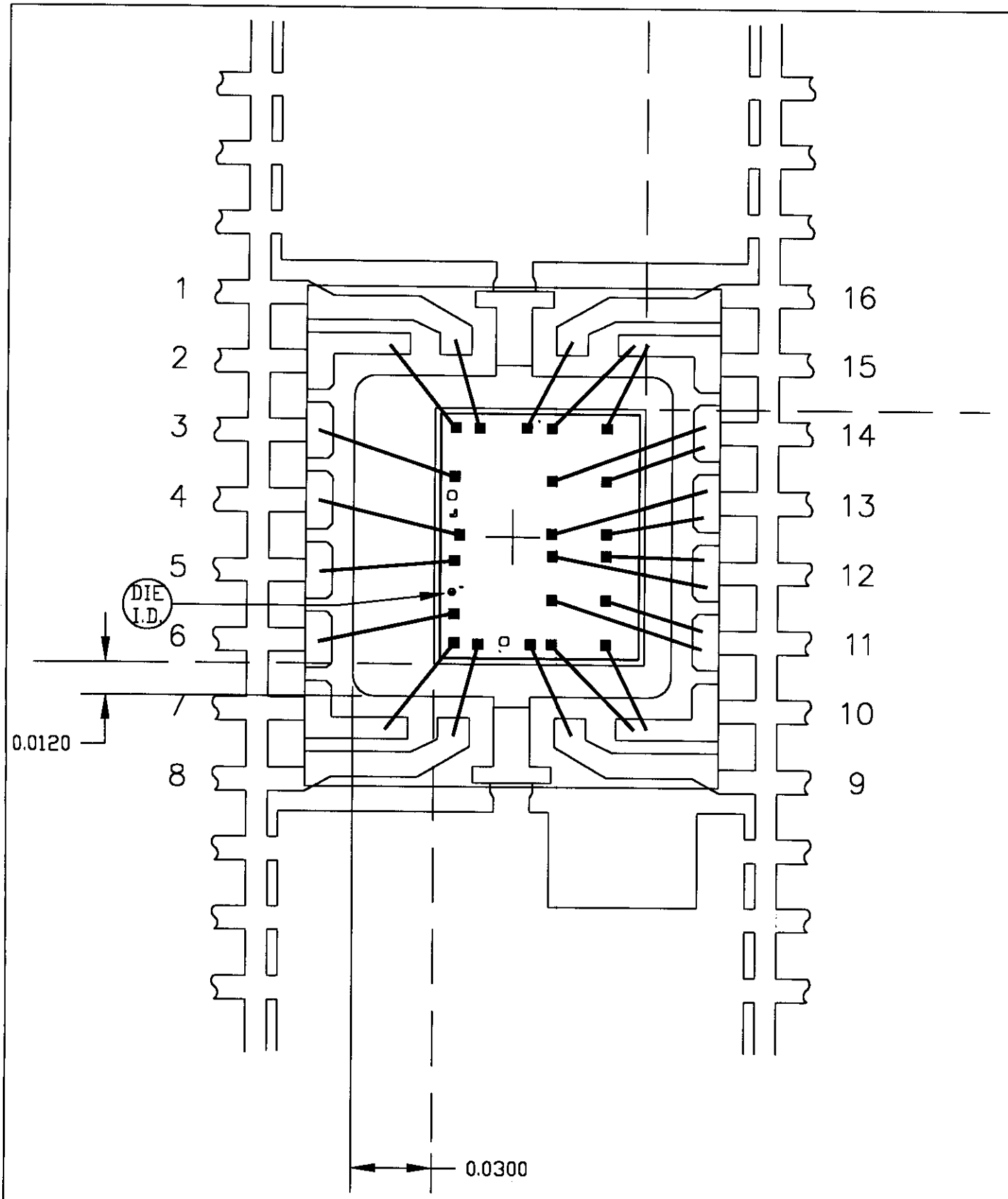
a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.

b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1}, or V_{SS2} or V_{SS3} or V_{CC1}, or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.

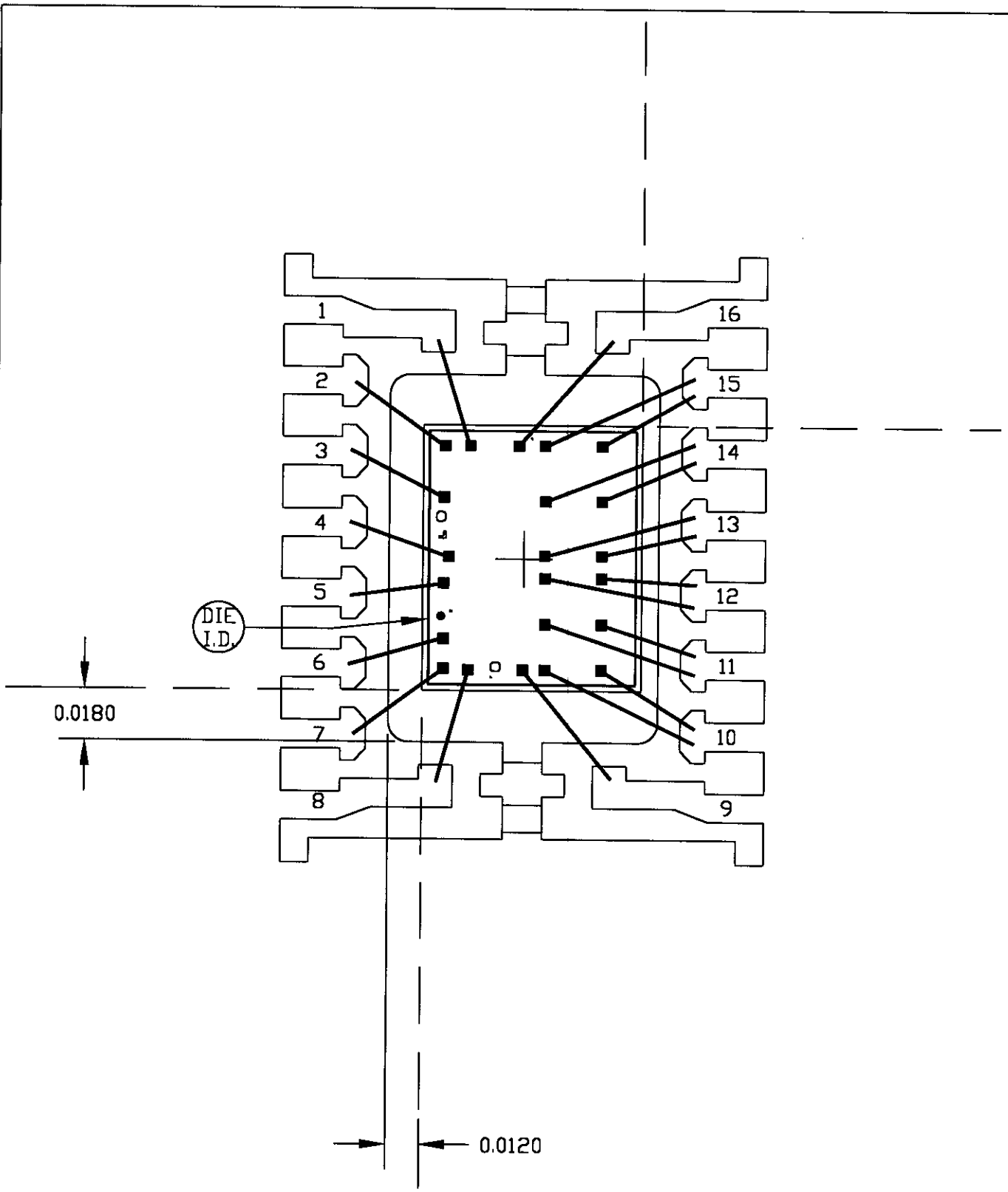
c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.



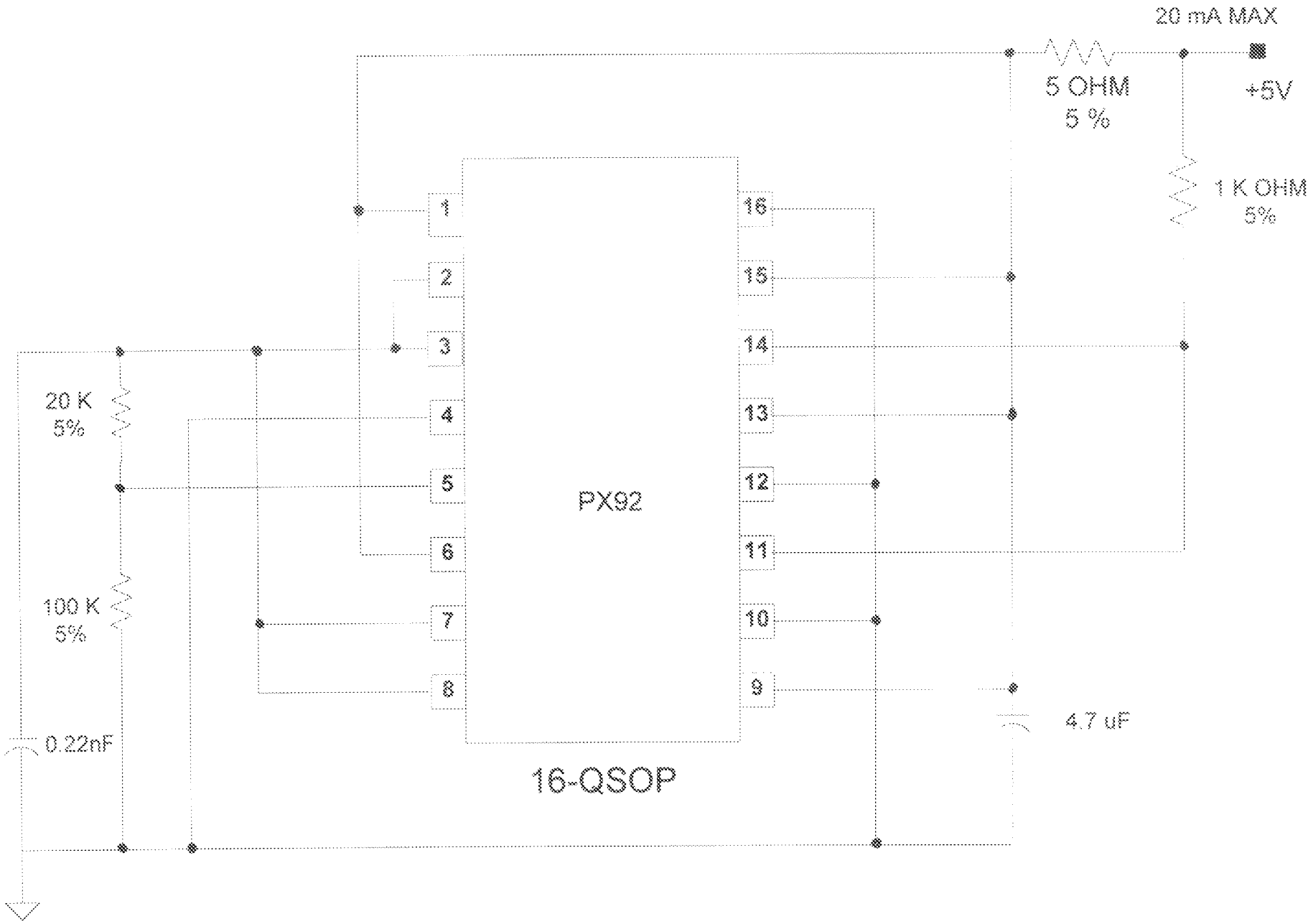
Mil Std 883D
Method 3015.7
Notice 8



PKG.CODE: U16E-3		APPROVALS	DATE	MAXIM
CAV./PAD SIZE: 118x118	PKG. DESIGN			BUILDSHEET NUMBER: 05-1101-0128 / REV.: A



PKG.CODE: E16-1		APPROVALS	DATE	MAXIM
CAV./PAD SIZE: 96X130	PKG. DESIGN			BUILDSHEET NUMBER: 05-1101-0127 / REV.: A



MAXIM BURN-IN SCHEMATIC	SPEC. 06-5482 REV. B DATE: 01/19/2000	DRAWN BY	DEVICE TYPES: MAX1763